### Fabrication Chart

<table>
<thead>
<tr>
<th>Finished Thickness</th>
<th>Silkscreen</th>
<th>Soldermask</th>
<th>Finished Copper Weight</th>
</tr>
</thead>
<tbody>
<tr>
<td>-0.031</td>
<td>Layer 1</td>
<td>Layer 1</td>
<td>1 oz.</td>
</tr>
<tr>
<td>-0.062</td>
<td>Layer 2</td>
<td>Layer 2</td>
<td>2 oz.</td>
</tr>
<tr>
<td>-0.093</td>
<td>None</td>
<td>None</td>
<td>Other</td>
</tr>
<tr>
<td>0.125</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Design</th>
<th>Trace/Gap Spacing</th>
<th>Layer Count</th>
</tr>
</thead>
<tbody>
<tr>
<td>SMD</td>
<td>0.030/0.030</td>
<td>Single Sided</td>
</tr>
<tr>
<td>Thru-Hole</td>
<td>0.030/0.007</td>
<td>2 Layer</td>
</tr>
<tr>
<td>Mix</td>
<td>0.030/0.006</td>
<td>4 Layer</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Other</td>
</tr>
</tbody>
</table>

### Notes: Unless Otherwise Specified

1. **Material:** All materials, including but not limited to base laminate, bonding materials, and soldermask coatings forming the finished printed circuit board shall meet UL-796 requirements and be RoHS complaint and have a flammability of UL-94V-0. Plastic sheet, laminated metal clad, one or two sides, base material NEA Type FR-4 or equivalent, Wt, =3.10 Deg C or higher. Minimum decomposition temp (Td) of 320 Deg C. Glass epoxy resin, copper clad in accordance with 2 layer stack up, compliant with lead free process.

2. **Base Laminate:** Soldermask over bare copper (SMD) using liquid photo-imageable soldermask in accordance with IPC-SM-840. Color: green. Minor soldermask adjustments to facilitate PCB fab and or assembly is allowed provided no defects are created to final assembly as a result.

3. **Soldermask:** Soldermask of SMD in accordance with IPC-SM-840. Color: green. Minor soldermask adjustments to facilitate PCB fab and or assembly is allowed provided no defects are created to final assembly as a result.

4. **Tolerances:** Unless otherwise specified PCB tolerances shall be +/- .005 inches. Hole diameters shall be +/- .003 inches.

5. **Plating:** Holes requiring plating, see hole chart, to have 1 oz. (0.0304) Min. Thk. Min. Copper.

6. **Finish:** Plate with RoHS compliant immersion silver preferred, immersion tin or Sn/Ag/Cu, with RMA flux, 0.002", 0.003" thick. All exposed areas as coated, no active fluxes are acceptable.

7. **Legend:** If required, silkscreen legend(s) with white non-conductive epoxy ink.

8. **Markings:** Board must bear vendor’s identification code (etch or white non-conductive ink). Location optional.

9. **Workmanship:** Board is to be manufactured per IPC-A-600 Class 2 requirements or better.

10. **Documentation:** PCB vendor is required to return any and all documents supplied or ultimately purchased by Texas Instruments upon completion of purchase order.

11. **Drill Sizes:** Hole diameters shown are finished sizes after plating unless otherwise noted.

12. **Panel Border:** Any metal in border area including part number, datecode and/or revision letters must be covered with soldermask.

13. **Process Changes:** No dimensional, material, or process changes are allowed without prior explicit written permission from Texas Instruments.
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